

PIN DESCRIPTIONS

PIN	SYMBOL	FUNCTION	DESCRIPTION
1	VCONT A/B	analog input	Transmit output amplitude control (0 - 5 Vdc, see Figure 4)
2	BUSA	analog output	MIL-STD-1533 bus driver A, positive signal
3	\overline{BUSA}	analog output	MIL-STD-1553 bus driver A, negative signal
4	RXENA	digital input	Receiver A enable. If low, forces RXA and \overline{RXA} low
5	GND A	power supply	Ground for bus A
6	VDDA/B	power supply	+5 volt power for both bus A and bus B
7	BUSB	analog output	MIL-STD-1533 bus driver B, positive signal
8	\overline{BUSB}	analog output	MIL-STD-1553 bus driver B, negative signal
9	RXENB	digital input	Receiver B enable. If low, forces RXB and \overline{RXB} low
10	GND B	power supply	Ground for bus B
11	\overline{RXB}	digital output	Receiver B output, inverted
12	RXB	digital output	Receiver B output, non-inverted
13	TXINH B	digital input	Transmit inhibit, bus B. If high BUSB, \overline{BUSB} disabled
14	TXB	digital input	Transmitter B digital data input, non-inverted
15	\overline{TXB}	digital input	Transmitter B digital data input, inverted
16	\overline{RXA}	digital output	Receiver A output, inverted
17	RXA	digital output	Receiver A output, non-inverted
18	TXINH A	digital input	Transmit inhibit, bus A. If high BUSA, \overline{BUSA} disabled
19	TXA	digital input	Transmitter A digital data input, non-inverted
20	\overline{TXA}	digital input	Transmitter A digital data input, inverted

FUNCTIONAL DESCRIPTION

The HI-1570 data bus transceiver contains differential voltage source drivers and differential receivers. They are intended for applications using a MIL-STD-1553 A/B data bus. The device produces a trapezoidal output waveform during transmission.

TRANSMITTER

Data input to the device's transmitter section is from the complementary CMOS / TTL inputs TXA/B and $\overline{TXA/B}$. The transmitter accepts Manchester II bi-phase data and converts it to differential voltages on BUSA/B and $\overline{BUSA/B}$. The transceiver outputs are either direct or transformer coupled to the MIL-STD-1553 data bus. Both coupling methods produce a nominal voltage on the bus of 7.5 volts peak to peak at VCONT A&B = 5.0 Vdc. Refer to Figure 4 for transmitter output amplitudes at other values of VCONT A&B between 0 - 5 Vdc. (Contact your Holt Sales Representative about the 0 - 10 Vdc Control Voltage option).

The transmitter is automatically inhibited and placed in the high impedance state when both TXA/B and $\overline{TXA/B}$ are either at a logic "1" or logic "0" simultaneously. A logic "1" applied to the TXINH A/B input will force the transmitter to the high impedance state, regardless of the state of TXA/B and $\overline{TXA/B}$.

RECEIVER

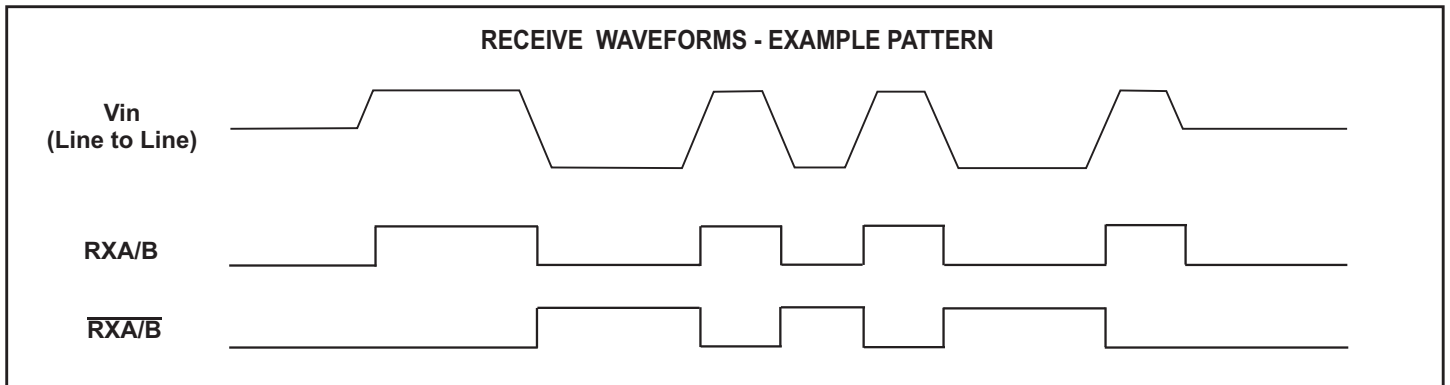
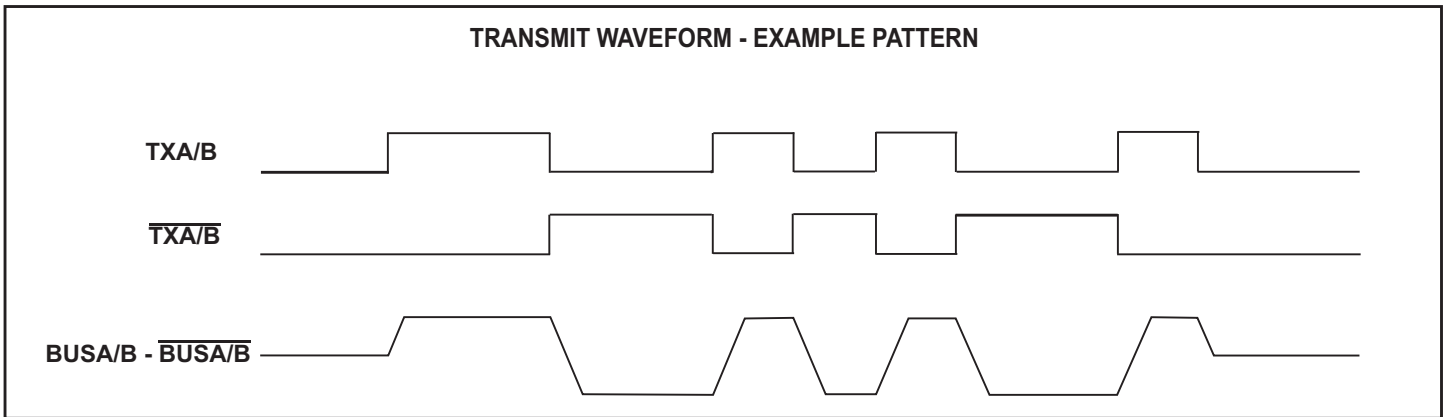
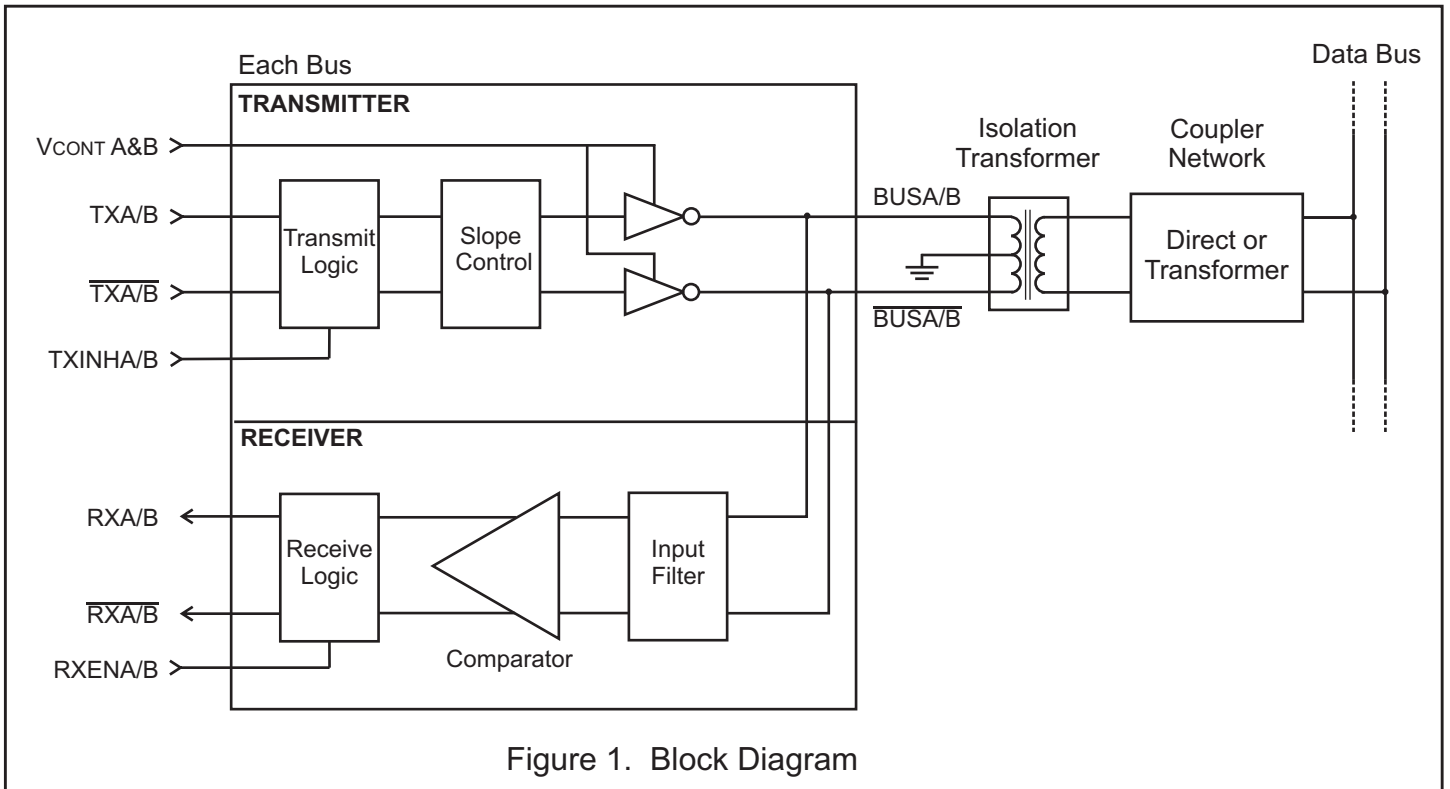
The receiver accepts bi-phase differential data from the MIL-STD-1553 bus through the same direct or transformer coupled interface as the transmitter. The receiver's differential input stage drives a filter and threshold comparator that produces CMOS/TTL data at the RXA/B and $\overline{RXA/B}$ output pins.

Each set of receiver outputs can be independently forced to a logic "0" by setting RXENA or RXENB low.

MIL-STD-1553 BUS INTERFACE

A direct coupled interface (see Figure 2) uses a 1:2.5 ratio isolation transformer and two 55 ohm isolation resistors between the transformer and the bus.

In a transformer coupled interface (see Figure 3), the transceiver is connected to a 1:1.79 isolation transformer which in turn is connected to a 1:1.4 coupling transformer. The transformer coupled method also requires two coupling resistors equal to 75% of the bus characteristic impedance (Z_0) between the coupling transformer and the bus.



ABSOLUTE MAXIMUM RATINGS

Supply voltage (VDD)	-0.3 V to +7 V
Logic input voltage range	-0.3 V dc to +5.5 V
Receiver differential voltage	10 Vp-p
Driver peak output current	+1.0 A
Reflow Solder Temperature	260°C
Junction Temperature	175°C
Storage Temperature	-65°C to +150°C

RECOMMENDED OPERATING CONDITIONS

Supply Voltage
VDD..... 5V... ±5%
Temperature Range
Industrial Screening.....-40°C to +85°C
Hi-Temp Screening.....-55°C to +125°C

NOTE: Stresses above absolute maximum ratings or outside recommended operating conditions may cause permanent damage to the device. These are stress ratings only. Operation at the limits is not recommended.

DC ELECTRICAL CHARACTERISTICS

VDD = 5.0V, GND = 0V, VCONT A/B = 5.0V, TA = Operating Temperature Range (unless otherwise specified).

PARAMETER	SYMBOL	CONDITION	MIN	TYP	MAX	UNITS
Operating Voltage	VDD		4.75	5	5.25	V
Total Supply Current	ICC1	Not Transmitting		20	30	mA
	ICC2	Transmit one bus @ 50% duty cycle		200	340	mA
	ICC3	Transmit one bus @ 100% duty cycle		400	550	mA
Power Dissipation	PD1	Not Transmitting			0.11	W
	PD2	Transmit one bus @ 100% duty cycle		0.70	0.95	W
Min. Input Voltage (HI)	V _{IH}	Digital inputs	2.0	1.4		V
Max. Input Voltage (LO)	V _{IL}	Digital inputs		1.4	0.8	V
Min. Input Current (HI)	I _{IH}	V _{IH} = 4.9V, Digital inputs			20	µA
Max. Input Current (LO)	I _{IL}	V _{IL} = 0.1V, Digital inputs	-20			µA
Min. Output Voltage (HI)	V _{OH}	I _{OUT} = -0.4mA, Digital outputs	2.7			V
Max. Output Voltage (LO)	V _{OL}	I _{OUT} = 4.0mA, Digital outputs			0.4	V

RECEIVER (Measured at Point "Ad" in Figure 3 unless otherwise specified)						
Input resistance	R _{IN}	Differential	20			kΩ
Input capacitance	C _{IN}	Differential			5	pF
Common mode rejection ratio	CMRR		40			dB
Input Level	V _{IN}	Differential			9	Vp-p
Input common mode voltage	V _{ICM}		-5.0		5.0	V-pk
Threshold Voltage - Direct-coupled	Detect	V _{THD}	1 MHz Sine Wave Measured at Point "Ad" in Figure 3 RXA/B, $\overline{RXA/B}$ pulse width 70 ns	1.15	20.0	Vp-p
Theshold Voltage - Transformer-coupled	Detect	V _{THD}	1 MHz Sine Wave Measured at Point "Ar" in Figure 4 RXA/B, $\overline{RXA/B}$ pulse width 70 ns	0.86	14.0	Vp-p

DC ELECTRICAL CHARACTERISTICS (cont.)

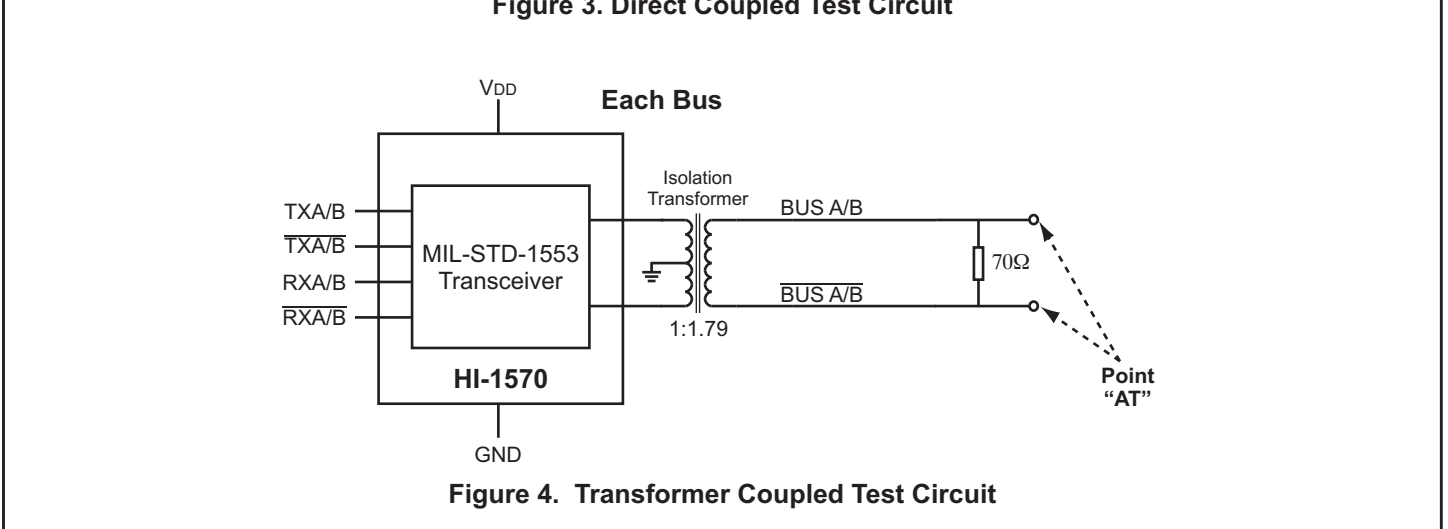
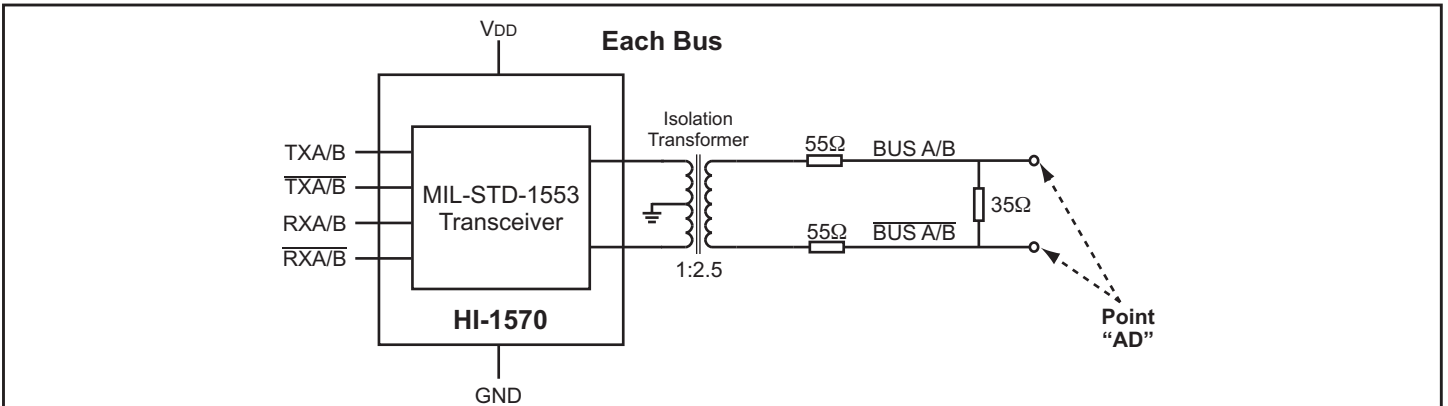
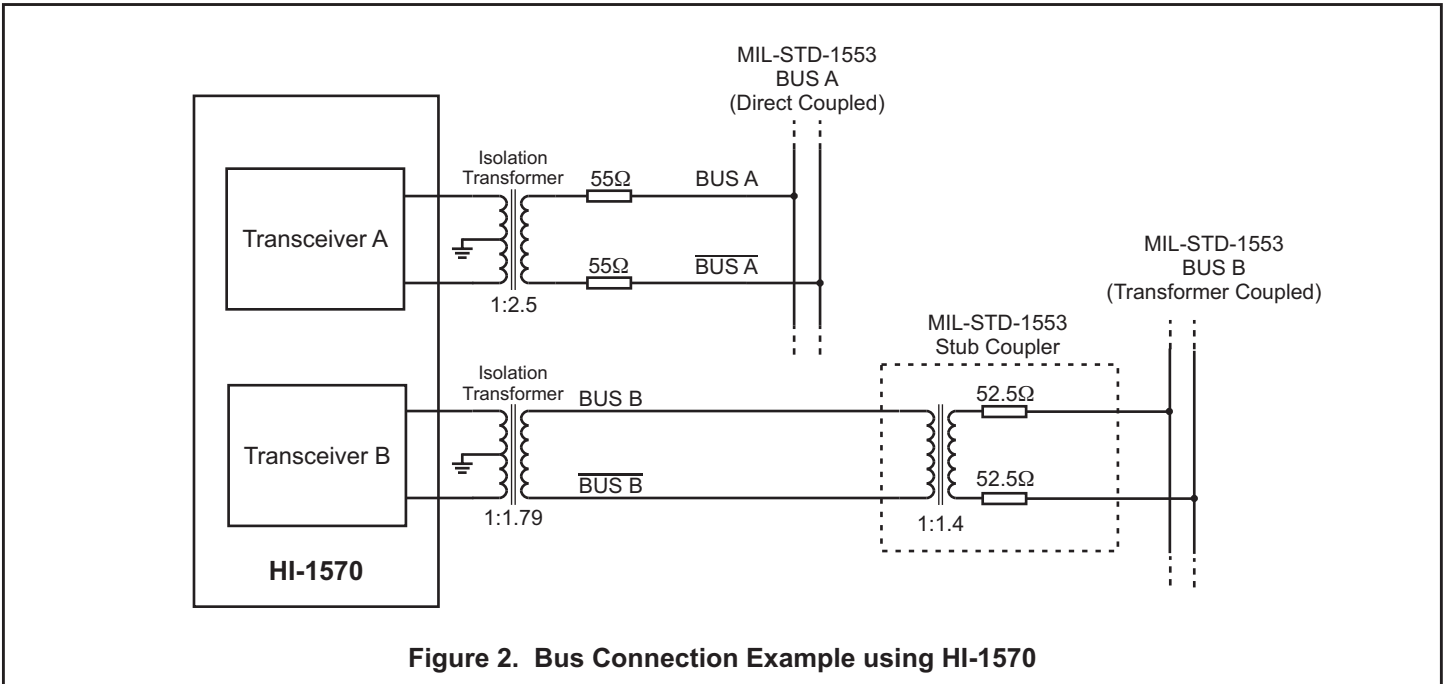
VDD = 5.0V, GND = 0V, VCONT A/B = 5.0V, TA = Operating Temperature Range (unless otherwise specified).

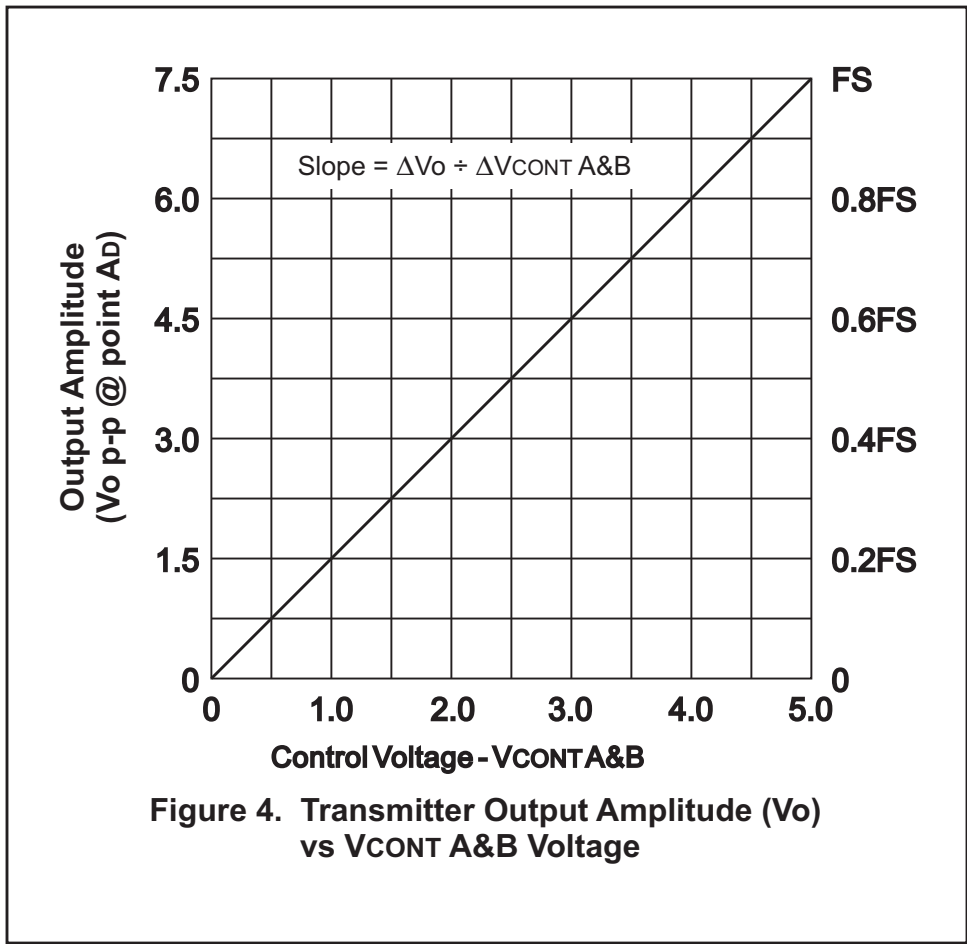
PARAMETER	SYMBOL	CONDITION	MIN	TYP	MAX	UNITS
TRANSMITTER (Measured at Point "Ab" in Figure 3 unless otherwise specified)						
Output Voltage	Direct coupled	V _{OUT} 35Ω load (Measured at Point "Ab" in Figure 3)	7.0		9.0	Vp-p
	Transformer coupled	V _{OUT} 70Ω load (Measured at Point "At" in Figure 4)	20.0		27.0	Vp-p
Output Noise	V _{ON}	Differential, inhibited			10.0	mVp-p
Output Dynamic Offset Voltage	Direct coupled	V _{DYN} 35Ω load (Measured at Point "Ab" in Figure 3)	-90		90	mV
	Transformer coupled	V _{DYN} 70Ω load (Measured at Point "At" in Figure 4)	-250		250	mV
Output Resistance	R _{OUT}	Differential, not transmitting	10			kΩ
Output Capacitance	C _{OUT}	1 MHz sine wave			15	pF
Control Line Resistance	R _{CONT}			5		kΩ

AC ELECTRICAL CHARACTERISTICS

VDD = 5.0V, GND = 0V, VCONT A/B = 5.0V, TA = Operating Temperature Range (unless otherwise specified).

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
RECEIVER (Measured at Point "At" in Figure 4 unless otherwise specified)						
Receiver Delay	t _{DR}	From input zero crossing to RXA/B or $\overline{RXA/B}$			450	ns
Receiver gap time	t _{RG}	Spacing between RXA/B and $\overline{RXA/B}$ pulses. 1 MHz sine wave applied at point "AT" Figure 4, amplitude range 0.86 Vp-p to 27.0Vp-p	90		365	ns
Receiver Enable Delay	t _{REN}	From RXENA/B rising or falling edge to RXA/B or $\overline{RXA/B}$			40	ns
TRANSMITTER (Measured at Point "Ad" in Figure 3)						
Driver Delay	t _{DT}	TXA/B, $\overline{TXA/B}$ to BUSA/B, $\overline{BUSA/B}$			150	ns
Rise time	t _r	35 ohm load	100		300	ns
Fall Time	t _f	35 ohm load	100		300	ns
Inhibit Delay	t _{DI-H}	Inhibited output			100	ns
	t _{DI-L}	Active output			150	ns





HEAT SINK - ESOIC PACKAGE

The HI-1570PSI/T/M all use a 20-pin thermally enhanced SOIC package. The package include a metal heat sink located on the bottom surface of the device. The heat sink should be soldered down to the printed circuit board for optimum thermal dissipation. The heat sink is also electrically isolated and may be soldered to any convenient power or ground plane.

APPLICATIONS NOTE

Holt Applications Note AN-500 provides circuit design notes regarding the use of Holt's family of MIL-STD-1553 transceivers. Layout considerations, as well as recommended interface and protection components are included.

RECOMMENDED TRANSFORMERS

The HI-1570 transceiver have been characterized for compliance with the electrical requirements of MIL-STD-1553 when used with the following transformers.

Holt recommends Premier Magnetics parts as offering the best combination of electrical performance, low cost and small footprint.

MANUFACTURER	PART NUMBER	APPLICATION	TURNS RATIO(S)	DIMENSIONS
Premier Magnetics	PM-DB2725EX	Isolation	Dual ratio 1:1.79, 1:2.5	0.4 x 0.4 x 0.242 inches
Premier Magnetics	PM-DB2702	Stub coupling	1:1.4	.625 x .625 x .250 inches
Premier Magnetics	PM-DB-2791S	Isolation	1:2.5	0.4 x 0.4 x 0.185 inches
Premier Magnetics	PM-DB-2795S	Isolation	1:1.79	0.4 x 0.4 x 0.185 inches
Premier Magnetics	PM-DB-2798S	Isolation	Dual ratio 1:1.79, 1:2.5	0.4 x 0.4 x 0.185 inches
Premier Magnetics	PM-DB-2762	Isolation	Dual core 1:2.5	0.4 x 0.4 x 0.320 inches
Premier Magnetics	PM-DB-2766	Isolation	Dual core 1:1.79	0.4 x 0.4 x 0.320 inches

ORDERING INFORMATION

HI - 1570PS x x (Plastic)

PART NUMBER	LEAD FINISH
Blank	Tin / Lead (Sn / Pb) Solder
F	100% Matte Tin (Pb-free, RoHS compliant)

PART NUMBER	TEMPERATURE RANGE	FLOW	BURN IN
I	-40°C TO +85°C	I	NO
T	-55°C TO +125°C	T	NO
M	-55°C TO +125°C	M	YES

PART NUMBER	RXENA = 0		RXENB = 0		PACKAGE DESCRIPTION
	RXA	$\overline{\text{RXA}}$	RXB	$\overline{\text{RXB}}$	
1570PS	0	0	0	0	20 PIN PLASTIC ESOIC, Thermally Enhanced Wide SOIC with Heat Sink (20HWE)

ORDERING INFORMATION

HI - 1570PC x x (Plastic)

PART NUMBER	LEAD FINISH
Blank	NiPdAu
F	NiPdAu (Pb-free, RoHS compliant)

PART NUMBER	TEMPERATURE RANGE	FLOW	BURN IN
I	-40°C TO +85°C	I	NO
T	-55°C TO +125°C	T	NO

PART NUMBER	RXENA = 0		RXENB = 0		PACKAGE DESCRIPTION
	RXA	\overline{RXA}	RXB	\overline{RXB}	
1570PC	0	0	0	0	44 PIN PLASTIC CHIP-SCALE Package (QFN) (44PCS)

HI - 1570CD x (Ceramic)

PART NUMBER	TEMPERATURE RANGE	FLOW	BURN IN	LEAD FINISH
I	-40°C TO +85°C	I	NO	Gold (Pb-free, RoHS compliant)
T	-55°C TO +125°C	T	NO	Gold (Pb-free, RoHS compliant)
M	-55°C TO +125°C	M	YES	Tin / Lead (Sn / Pb) Solder

PART NUMBER	RXENA = 0		RXENB = 0		PACKAGE DESCRIPTION
	RXA	\overline{RXA}	RXB	\overline{RXB}	
1570CD	0	0	0	0	20 PIN CERAMIC SIDE BRAZED DIP (20C)

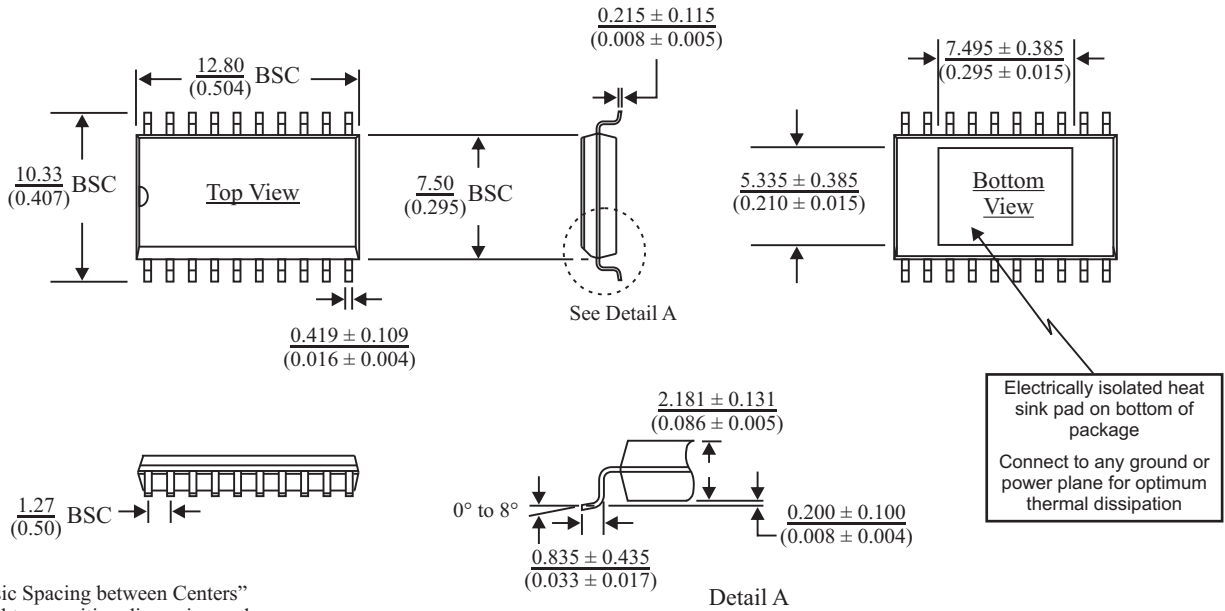
REVISION HISTORY

Document	Rev.	Date	Description of Change
DS1570	F	09/26/08	Clarification of transmitter and receiver functions in Description, clarified available temperature ranges, and corrected a dimension in Recommended Transformers table.
	G	07/24/09	Correct typographical errors in package dimensions.
	H	02/14/17	Update Direct and Transformer Coupled test circuits. Remove Thermal Characteristics Table. Update Recommended Transformers Table. Update Solder Temperature (reflow). Update Test Conditions in DC and AC Electrical Characteristics Table. Add Bus Connection example. Update 44PCS and 20HWE package drawings.
	J	09/03/2020	Correct typo in DC Electrical Characteristics Table; VOL incorrectly labeled as VIH. Remove Power Dissipation from Absolute Maximum Ratings Table. Update QFN package lead finish to NiPdAu.

20-PIN PLASTIC SMALL OUTLINE (ESOC) - WB
(Wide Body, Thermally Enhanced)

millimeters (inches)

Package Type: 20HWE

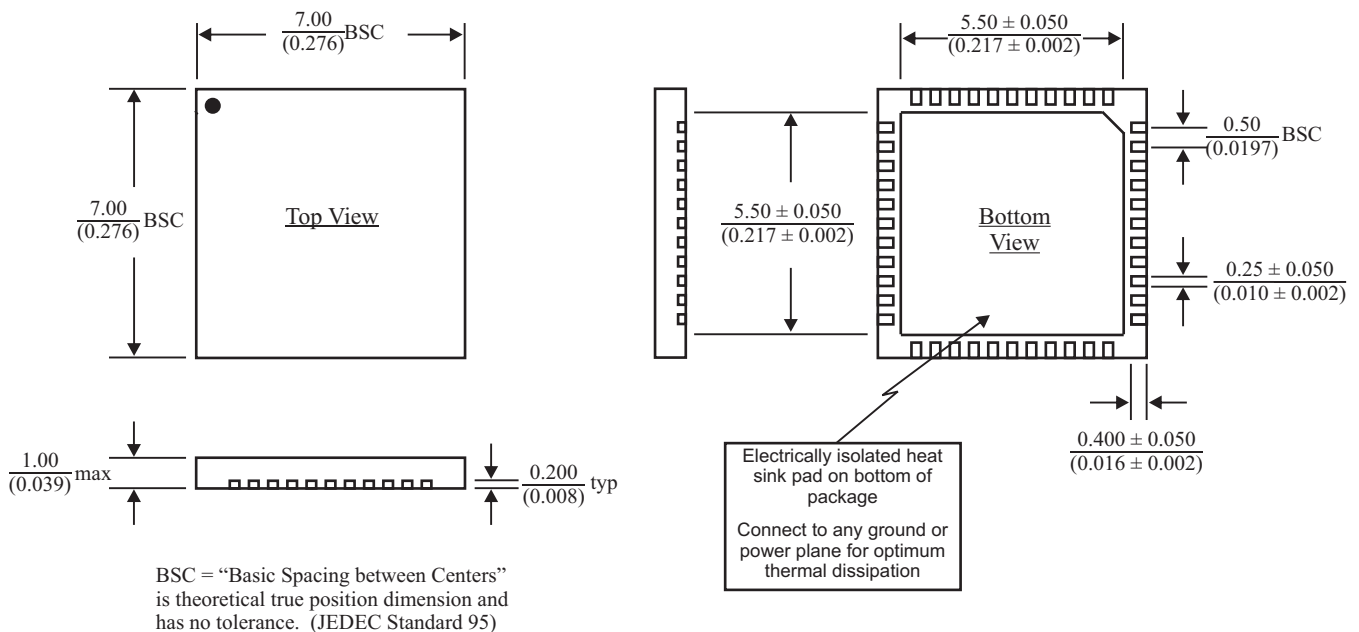


BSC = "Basic Spacing between Centers" is theoretical true position dimension and has no tolerance. (JEDEC Standard 95)

44-PIN PLASTIC CHIP-SCALE PACKAGE (QFN)

millimeters (inches)

Package Type: 44PCS

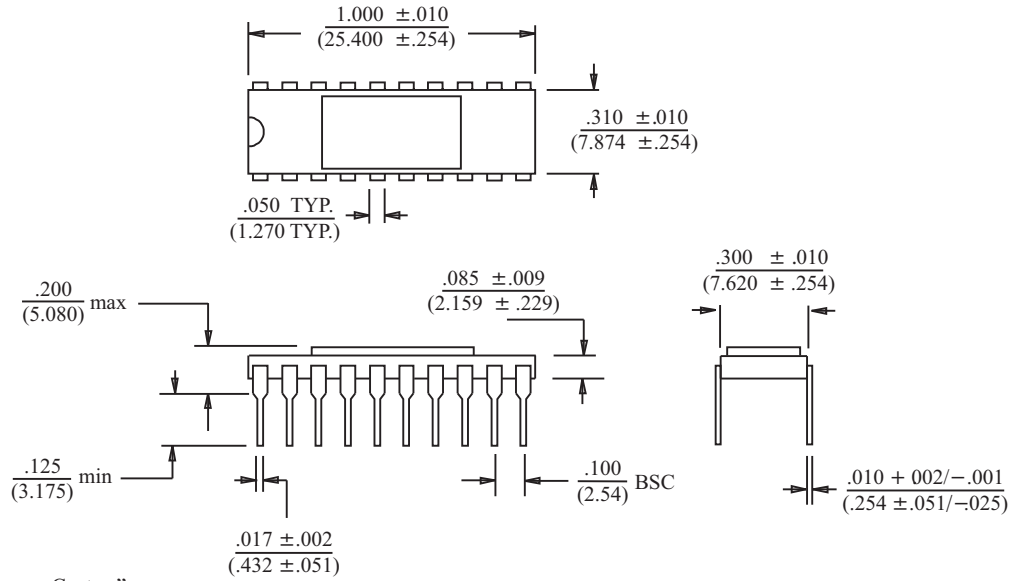


BSC = "Basic Spacing between Centers" is theoretical true position dimension and has no tolerance. (JEDEC Standard 95)

20-PIN CERAMIC SIDE-BRAZED DIP

inches (millimeters)

Package Type: 20C



BSC = "Basic Spacing between Centers" is theoretical true position dimension and has no tolerance. (JEDEC Standard 95)